

**Amendment and Response**

Applicant: Michael Bauer et al.

Serial No.: 10/789,033

Filed: February 27, 2004

Docket No.: 1431.103.101/FIN423US

Title: ELECTRONIC COMPONENT AND SEMICONDUCTOR WAFER, AND METHOD FOR PRODUCING THE SAME

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**IN THE CLAIMS**

Please amend claims 6, 13 and 14 as follows:

1.-5. (Cancelled)

6. (Currently Amended) A semiconductor chip system, comprising:  
a plurality of semiconductor chips, each having:  
    a top side, a rear side opposite and parallel to the top side, and edge sides;  
    an integrated circuit on the top side;  
    at least one edge side having edge contacts wherein the edge contacts extend from the top side in the direction of the rear side of the semiconductor chip;  
    wherein the edge contacts are connected to electrodes of the integrated circuit via conductor tracks located on the top surface of the semiconductor chip; and  
    a circuit substrate having a top side with external contacts, wherein the semiconductor chips are electrically connected via the edge contacts among one another and wherein the semiconductor chips are electrically connected via the edge contacts also with respect to the external contacts on the circuit substrate such that the top and rear sides of the semiconductor chips are oriented virtually perpendicular to the top side of the circuit substrate.
7. (Previously Presented) The semiconductor chip system of claim 6, wherein the edge sides have a perforation-like structure, semicylinder-like cutouts extending as edge contacts from the top side in the direction of the rear side, and have a metal layer.
8. (Previously Presented) The semiconductor chip system of claim 7, wherein the edge sides also have an insulation layer.

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9. (Previously Presented) The semiconductor chip system of claim 7, wherein the cutouts have a soldering material.

10. (Previously Presented) The semiconductor chip system of claim 7, wherein the edge contacts are extended on the top side to form a contact area and merge with a conductor track on the top side.

11. (Previously Presented) The semiconductor chip system of claim 7, wherein the semiconductor chips are arranged on the circuit substrate within an electronic component.

12. (Previously Presented) The semiconductor chip system of claim 11, wherein the external contacts on the top side of the circuit substrate is a conductor track structure having conductive lines running in parallel.

13. (Currently Amended) The semiconductor chip system of claim 12, wherein an insulating plastics composition is arranged on the circuit substrate in a manner embedding the edge sides of the semiconductor chip and the contact pads edge contacts.

14. (Currently Amended) The semiconductor chip system of claim 12, wherein the semiconductor chip is chips are arranged with an edge side on the circuit substrate, the top side of the semiconductor chips being arranged in angular fashion with respect to the top side of the circuit substrate and the edge contacts being electrically connected to the contact pads external contacts.

15-20. (Cancelled)